

# SOT1390-10

WLCSP12, wafer level chip-scale package, 12 terminals, 0.4 mm pitch, 1.97 mm x 1.42 mm x 0.525 mm body

11 July 2018

Package information

## 1 Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP12
<b>Package style descriptive code</b>	WLCSP (wafer level chip-size package)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	19-06-2018
<b>Manufacturer package code</b>	98ASA01259D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	-	1.97	-	mm
package width	-	1.42	-	mm
package height	-	0.525	-	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	12	-	



2 Package outline

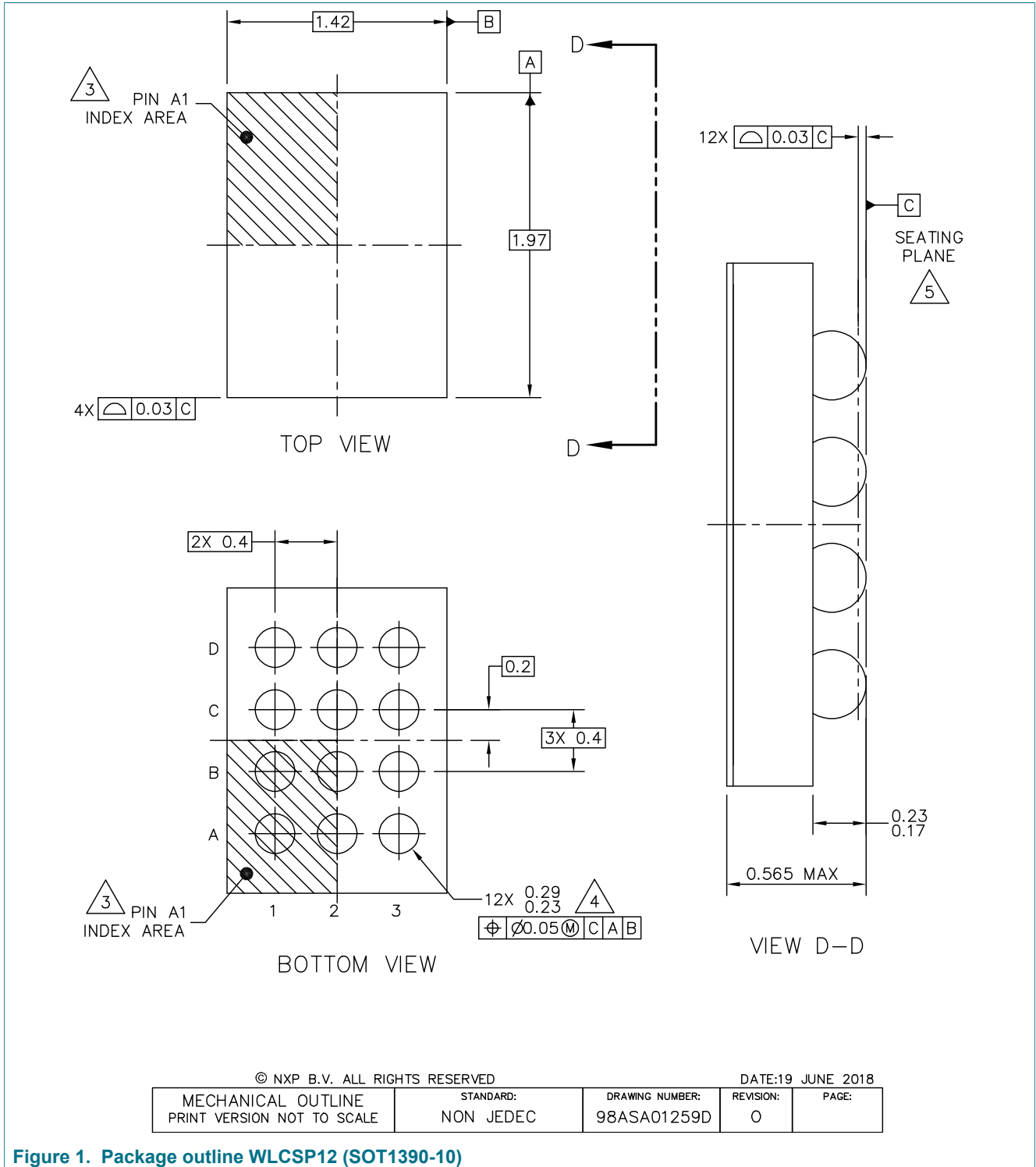


Figure 1. Package outline WLCSP12 (SOT1390-10)

NOTES:

1. ALL DIMENSIONS IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALL
6. THIS PACKAGE HAS A BACK SIDE COATING THICKNESS OF 0.025.

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DATE:19 JUNE 2018

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01259D	REVISION: 0	PAGE:
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Figure 2. Package outline note WLCSP12 (SOT1390-10)

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3 Soldering

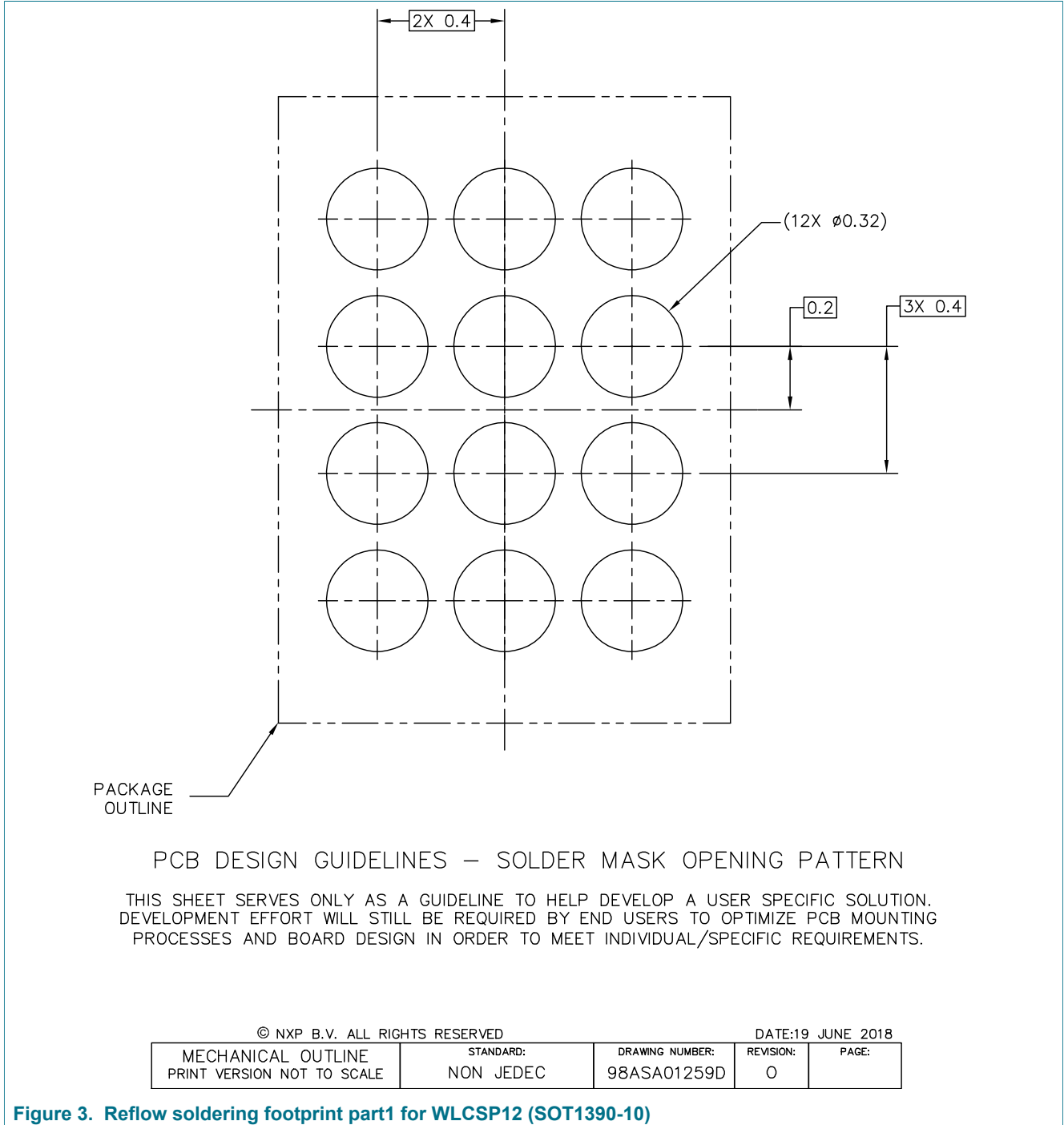


Figure 3. Reflow soldering footprint part1 for WLCSP12 (SOT1390-10)

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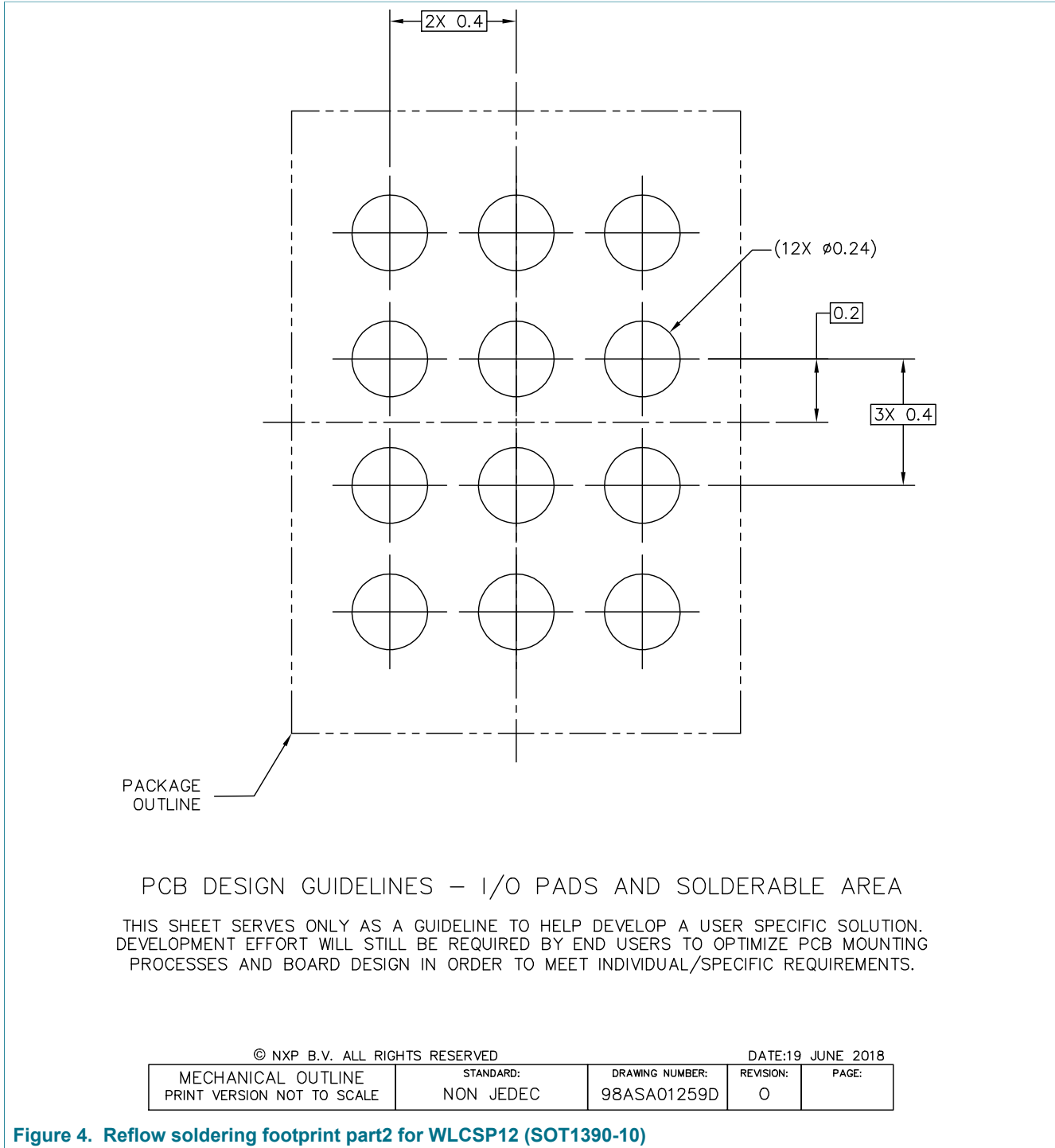


Figure 4. Reflow soldering footprint part2 for WLCSP12 (SOT1390-10)

WLCSP12, wafer level chip-scale package, 12 terminals, 0.4 mm pitch, 1.97 mm x 1.42 mm x 0.525 mm body

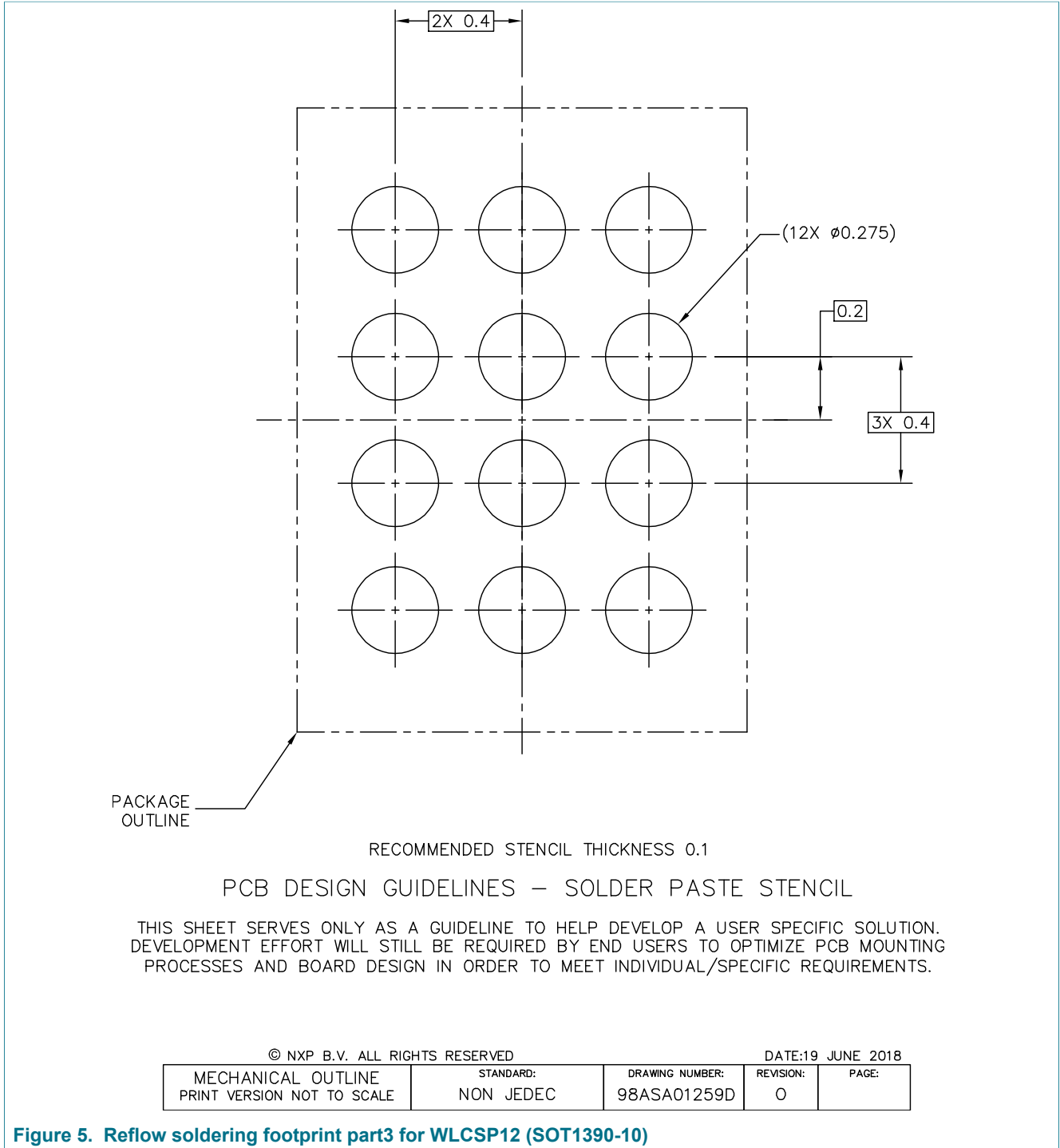


Figure 5. Reflow soldering footprint part3 for WLCSP12 (SOT1390-10)

## 4 Legal information

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